

PATENT APPLICATION

Docket No. 9903-074

Client No. S03US003

Applicant: Dong-Ho Lee

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For: STACK PACKAGE MADE OF CHIP SCALE PACKAGES

**INFORMATION DISCLOSURE CITATION
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FOREIGN PATENT DOCUMENTS

| <u>Exam Init</u> | <u>Ref</u> | <u>Document Number</u> | <u>Publication Date</u> | <u>Country</u> | <u>Name</u> |
|----------------------|------------|----------------------------|-----------------------------|----------------|--------------|
| _____ | _____ | JP2000-216327 | 4/8/2000 | Japan | Oda Toshiaki |
| _____ | _____ | KR2001-11310 | 2/15/2001 | Korea | Jang and Ko |
| _____ | _____ | KR2001-28845 | 4/6/2001 | Korea | Kim and Lee |

OTHER DOCUMENTS

| <u>Exam Init</u> | <u>Ref</u> | <u>Author, Title, Date, Pertinent Pages, Etc.)</u> |
|----------------------|------------|---|
| _____ | _____ | English language of Abstract for Japanese Patent Publication No. JP2000-216327, published 4/8/2000. |
| _____ | _____ | English language of Abstract for Korean Patent Publication No. KR2001-11310, published 2/15/2001. |
| _____ | _____ | English language of Abstract for Korean Patent Publication No. KR2001-28845, published 4/6/2001. |

Examiner: _____

Date Considered: _____